

OSG80R380FF_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

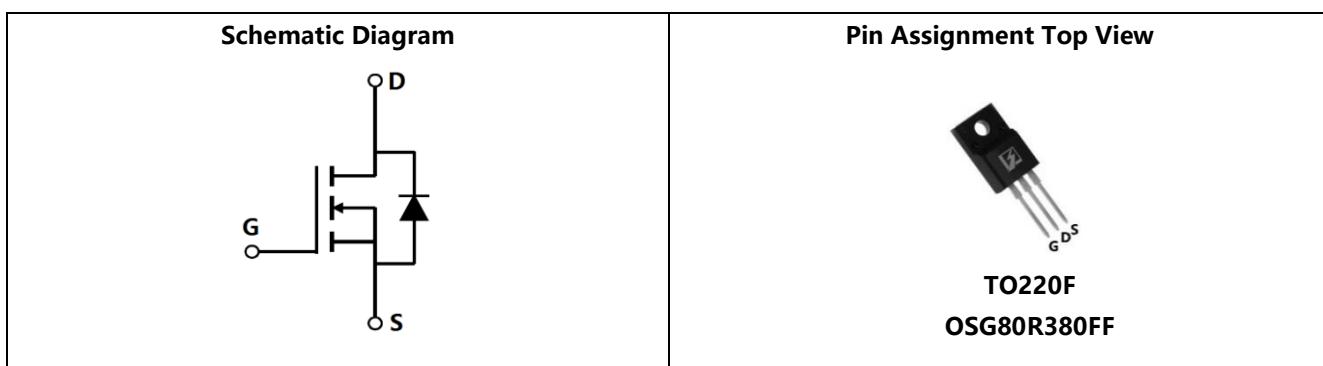
- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger

■ General Description

OSG80R380FF uses advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

◆ $V_{DS, min@Tjmax}$	850 V
◆ $I_D, pulse$	33 A
◆ $R_{DS(ON)}, \text{max } @ VGS=10 \text{ V}$	380 mΩ
◆ Q_g	22.2 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	800	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_c=25^\circ\text{C}$	I_D	11	A
Continuous drain current ¹⁾ , $T_c=100^\circ\text{C}$		6.9	
Pulsed drain current ²⁾ , $T_c=25^\circ\text{C}$	I_D, pulse	33	A
Power dissipation ³⁾ , $T_c=25^\circ\text{C}$	P_D	34	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	400	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...640 \text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...640 \text{ V}, I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	3.68	°C/W
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62.5	°C/W

■ Electrical Characteristics at $T_j=25$ °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	800			V	$V_{GS}=0$ V, $I_D=250$ μA
		850	950			$V_{GS}=0$ V, $I_D=250$ μA, $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	2.9		3.9	V	$V_{DS}=V_{GS}$, $I_D=250$ μA
Drain-source on-state resistance	$R_{DS(ON)}$		0.30	0.38	Ω	$V_{GS}=10$ V, $I_D=5.5$ A
			0.69			$V_{GS}=10$ V, $I_D=5.5$ A, $T_j=150$ °C
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	I_{DSS}			10	μA	$V_{DS}=800$ V, $V_{GS}=0$ V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		1442.9		pF	$V_{GS}=0$ V, $V_{DS}=50$ V, $f=100$ kHz
Output capacitance	C_{oss}		83.7		pF	
Reverse transfer capacitance	C_{rss}		1.9		pF	
Turn-on delay time	$t_{d(on)}$		28.4		ns	$V_{GS}=10$ V, $V_{DS}=400$ V, $R_G=10$ Ω, $I_D=6$ A
Rise time	t_r		15.8		ns	
Turn-off delay time	$t_{d(off)}$		50.2		ns	
Fall time	t_f		4.7		ns	

■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		22.2		nC	$I_D=6\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		6.8		nC	
Gate-drain charge	Q_{gd}		6.3		nC	
Gate plateau voltage	$V_{plateau}$		5.7		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			11	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			33		
Diode forward voltage	V_{SD}			1.3	V	$I_S=11\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		262.0		ns	$V_R=400\text{ V}, I_S=6\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		3.9		μC	
Peak reverse recovery current	I_{rrm}		29.1		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=25\text{ }\Omega$, $L=10\text{ mH}$, starting $T_j=25\text{ }^{\circ}\text{C}$.

■ Electrical Characteristics Diagrams

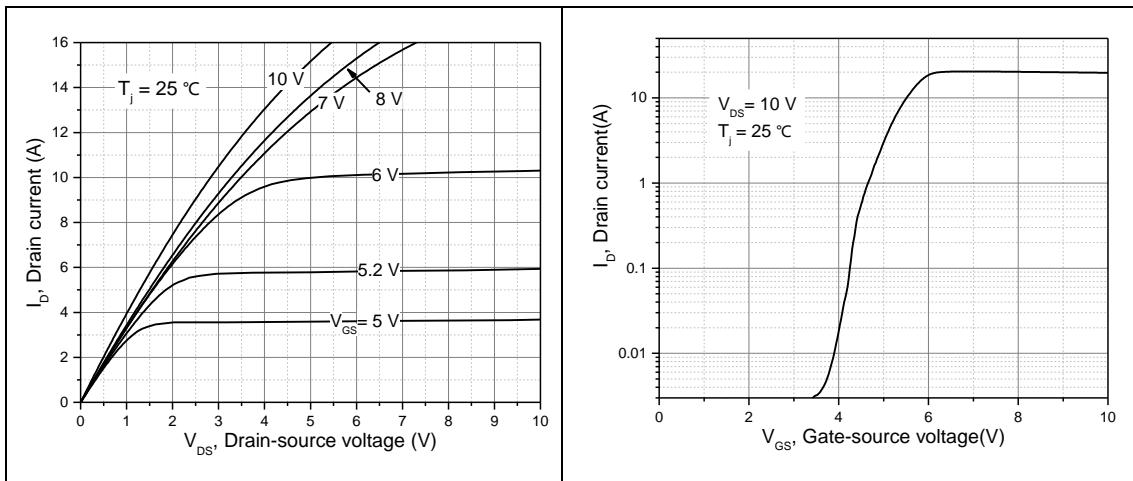


Figure 1, Typ. output characteristics

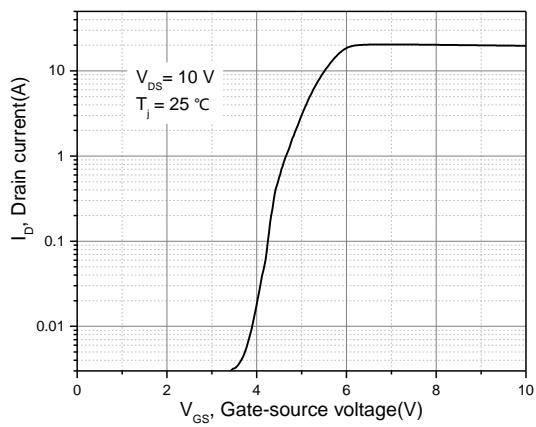


Figure 2, Typ. transfer characteristics

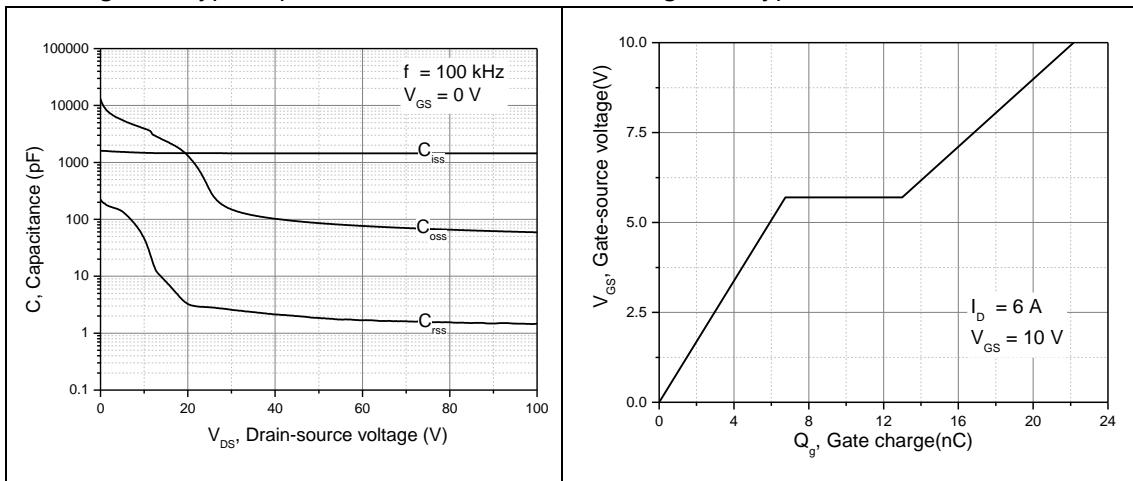


Figure 3, Typ. capacitances

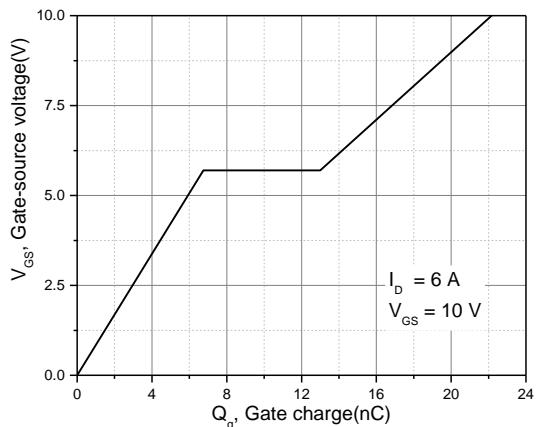


Figure 4, Typ. gate charge

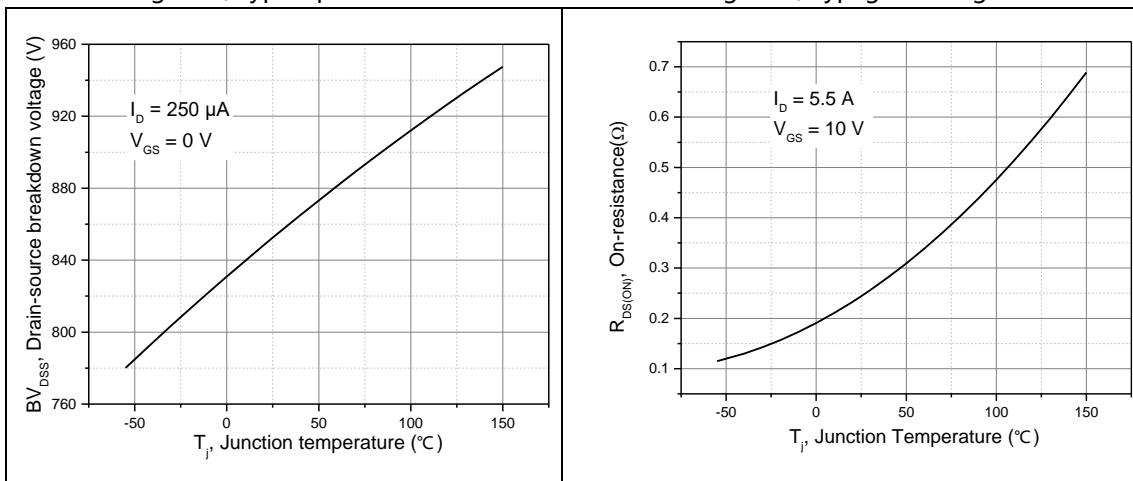


Figure 5, Drain-source breakdown voltage

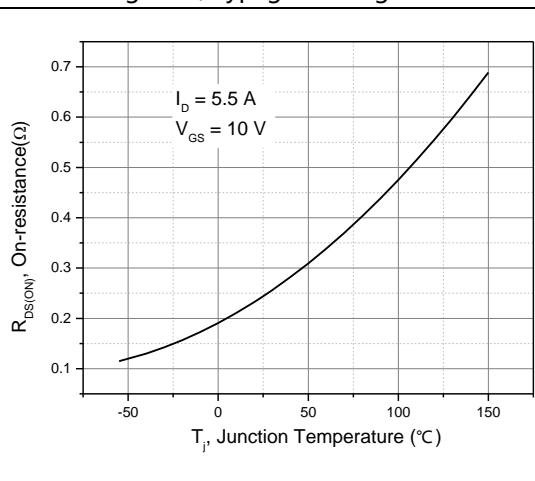


Figure 6, Drain-source on-state resistance

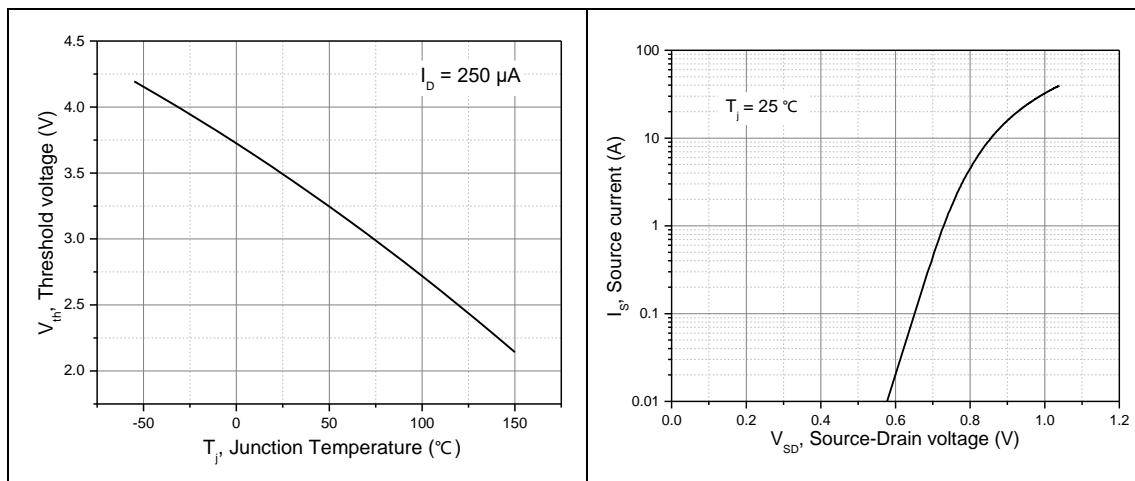


Figure 7, Threshold voltage

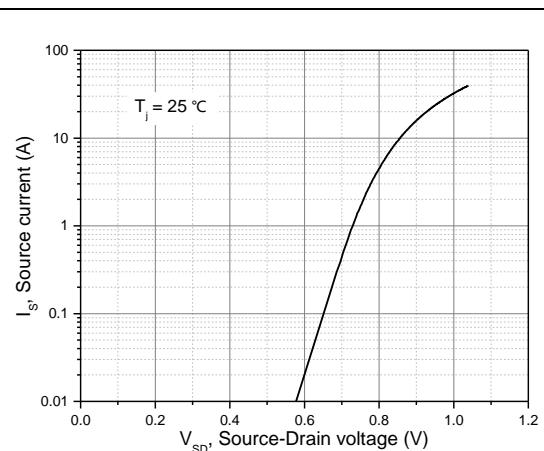


Figure 8, Forward characteristic of body diode

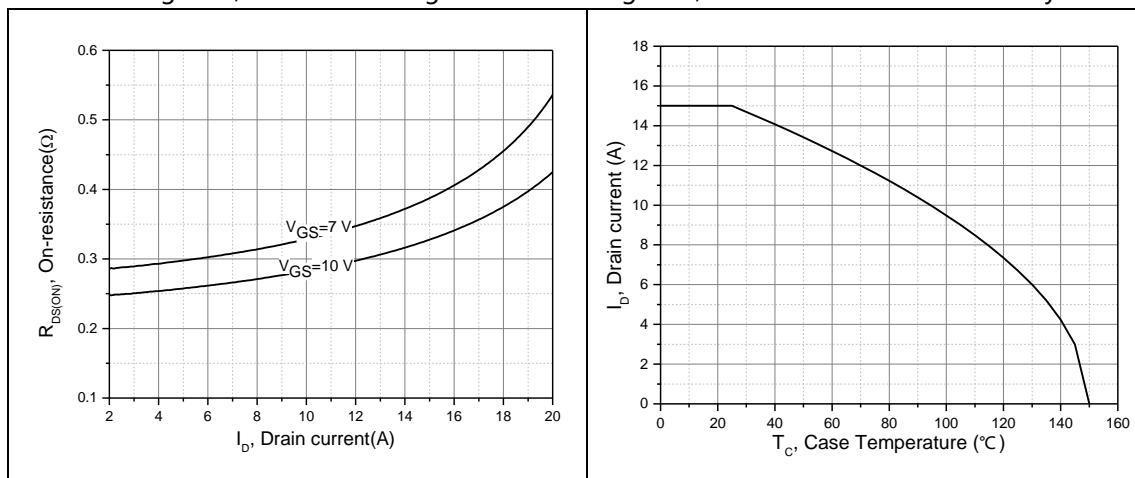


Figure 9, Drain-source on-state resistance

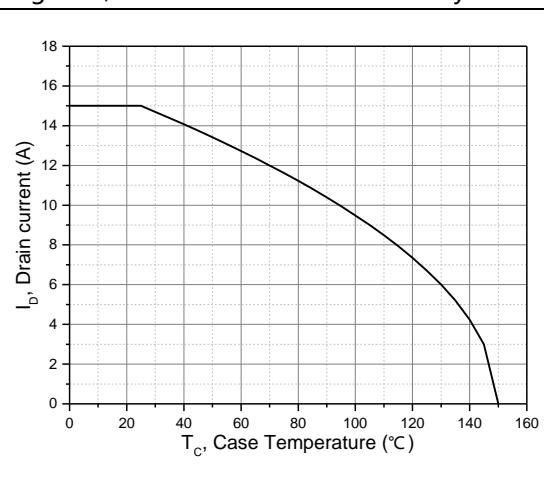


Figure 10, Drain current

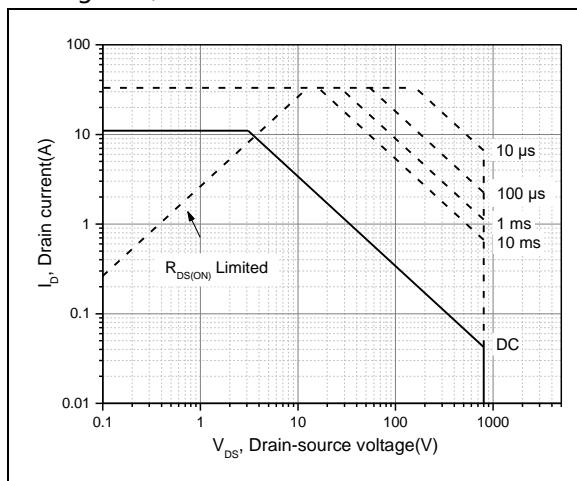


Figure 11, Safe operation area for TO220F

$T_C=25^\circ C$

■ Test circuits and waveforms

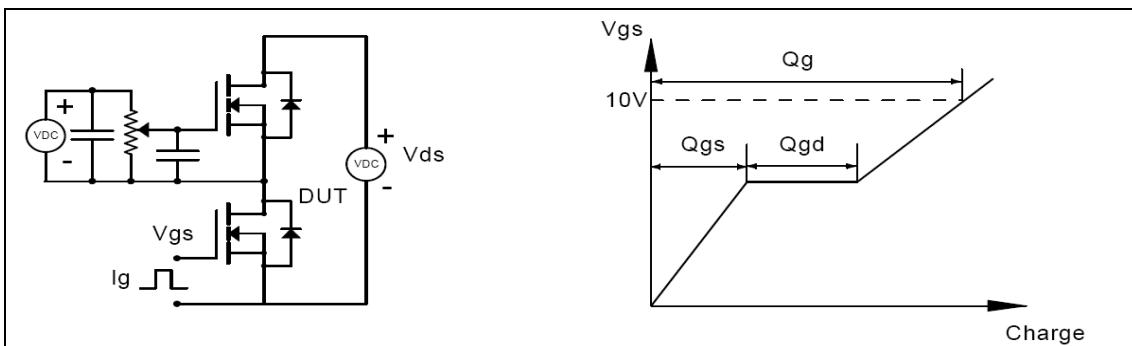


Figure 1, Gate charge test circuit & waveform

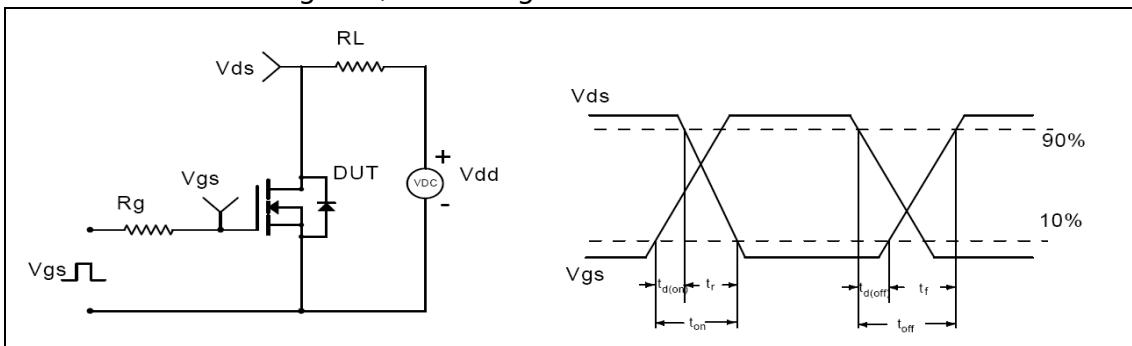


Figure 2, Switching time test circuit & waveforms

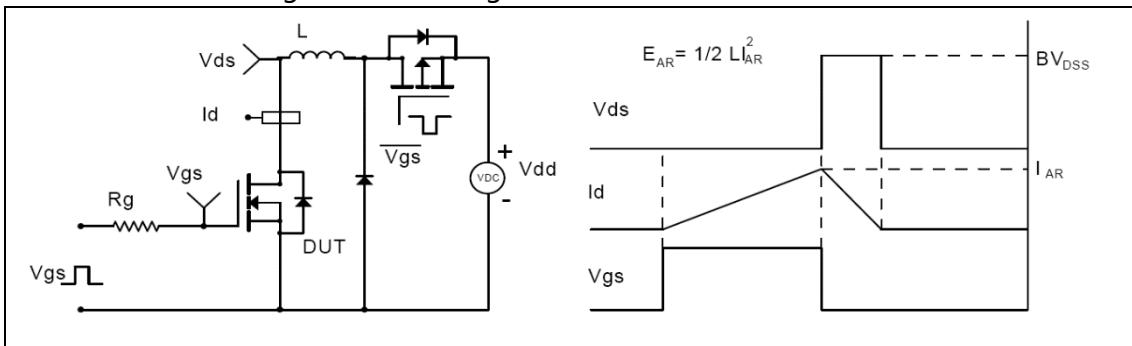


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

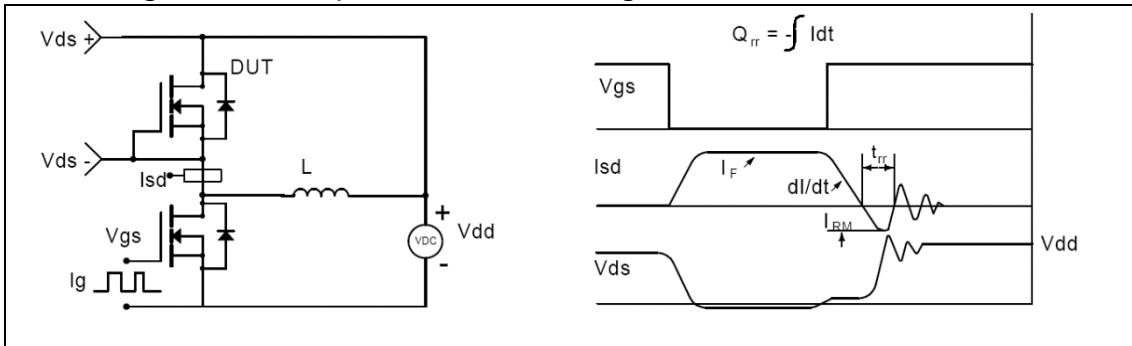
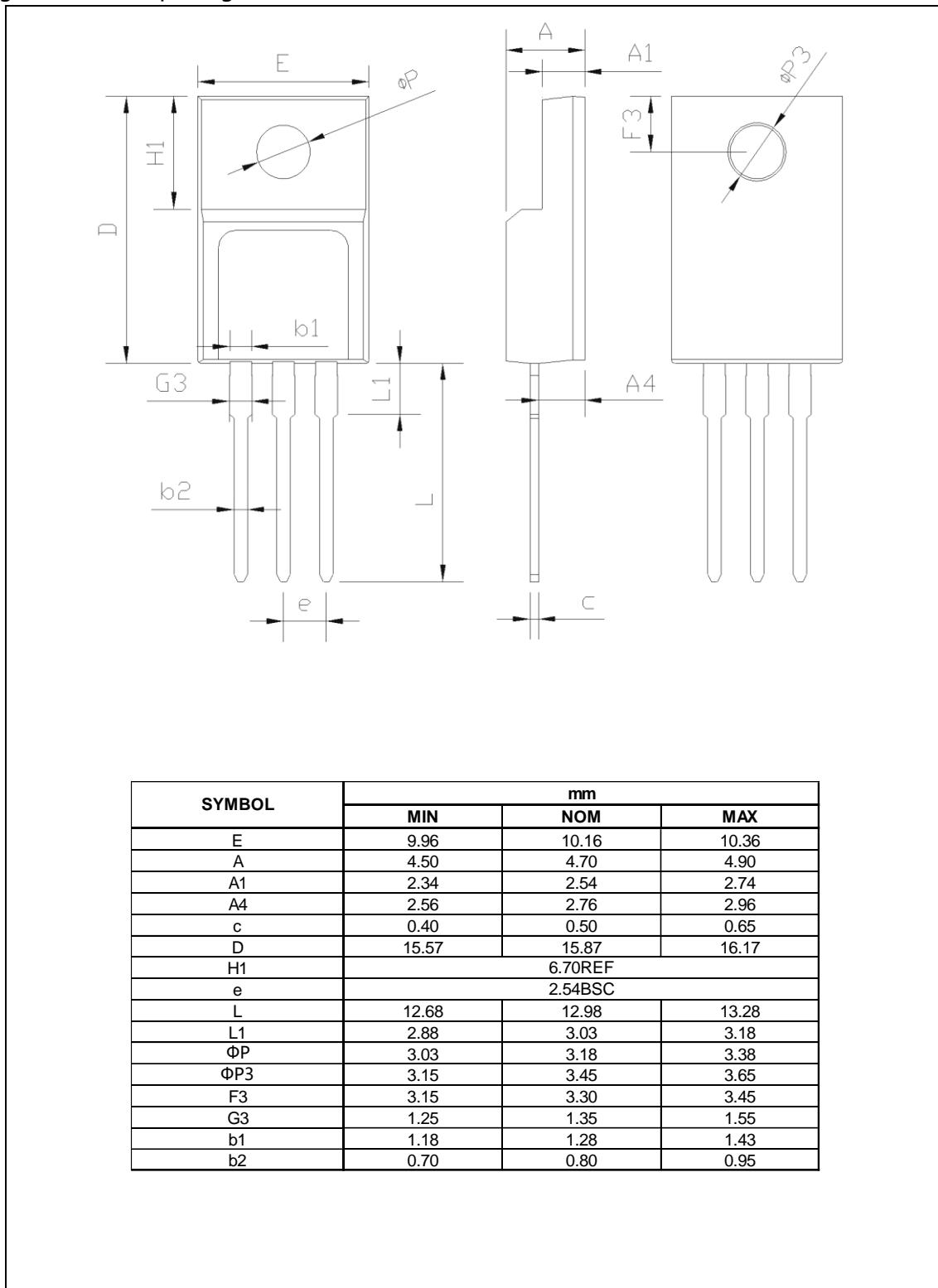


Figure 4, Diode reverse recovery test circuit & waveforms

■ Package Information

Figure1, TO220F package outline dimension



■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO220F	50	20	1000	6	6000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG80R380FF	TO220F	yes	yes	yes